Surface Mount

Phase Detector

50Ω High Output 1 to 100 MHz

SYPD-1+

Generic photo used for illustration purposes only

CASE STYLE: TTT167

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Maximum Ratings

Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
Input Power	50mW
Peak IF current	20mA

Permanent damage may occur if any of these limits are exceeded.

Pin Connections

RF REF (RF2)	2
RF IN (RF1)	1
DC OUT (I)	3
GROUND	4,5,6

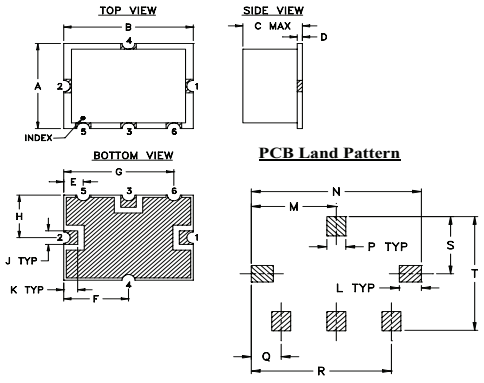
Features

- wideband, 1 to 100 MHz
- low DC offset, 0.2 mV typ.
- high DC output, 1000 mV typ.
- high isolation, 40 dB min.

Applications

- monitoring circuits
- leveling circuits
- PLL

Outline Drawing



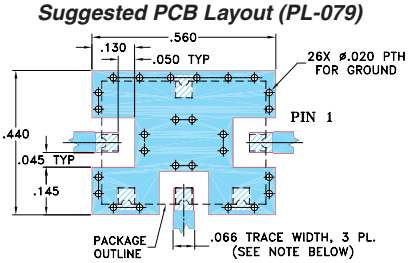
Suggested Layout,
Tolerance to be within ±.002

Outline Dimensions (inch / mm)

A	B	C	D	E	F	G	H	J	K
.38	.50	.23	.020	.075	.250	.425	.187	.050	.050
9.65	12.70	5.84	0.51	1.91	6.35	10.80	4.75	1.27	1.27

L	M	N	P	Q	R	S	T	wt.
.070	.270	.540	.060	.095	.445	.208	.415	grams
1.78	6.86	13.72	1.52	2.41	11.30	5.28	10.54	0.8

Demo Board MCL P/N: TB-12
Suggested PCB Layout (PL-079)



NOTE:

1. TRACE WIDTH IS SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .030" ± .002"; COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. THE USE OF SOLDER MASK OVER THE GROUND AREA UNDER THE UNIT AS SHOWN IS RECOMMENDED TO PREVENT POTENTIAL SHORTING. IF USER CHOOSES TO EXPOSE METAL UNDER THE ENTIRE UNIT GROUND PAD FOR IMPROVED GROUNDING, IT IS RECOMMENDED A SOLDER MASK DAM BE APPLIED AROUND EACH GROUND PAD TO ENSURE FILLET AND CONNECTION AT GROUND PADS.
3. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER), SEE NOTE 2.

DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

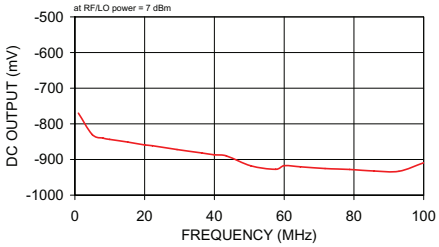
Electrical Specifications

FREQUENCY (MHz)		POWER IN	SCALE FACTOR	IMPEDANCE (ohms) Output Load	ISOLATION (dB)	OUTPUT POLARITY	DC OUTPUT (mV)				FIGURE OF MERIT
		RF1		I							
RF1	I	RF2			RF1/RF2	RF1/RF2	Max.		Offset		
RF2		(dBm)	mV/deg.		Min.	In-Phase	Typ.	Min.	Typ.	Max.	Typ.
1-100	DC-50	7	8	500	40	neg.	1000	700	0.2	1	143

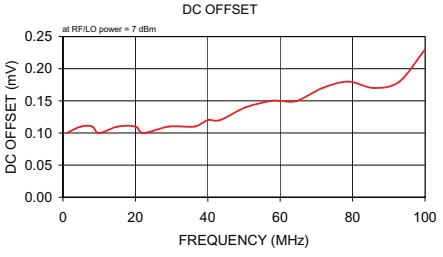
Typical Performance Data

Frequency (MHz)	DC Output mV		DC Offset mV		RF1-RF2 Isolation (dB)
	$\overline{X}$	σ	$\overline{X}$	σ	$\overline{X}$
1.00	-769.98	14.85	0.10	0.16	76.12
5.00	-830.34	8.90	0.11	0.18	75.09
8.07	-840.24	14.44	0.11	0.18	74.07
10.00	-843.71	14.61	0.10	0.18	73.19
15.14	-851.12	17.01	0.11	0.19	70.19
20.00	-859.20	18.91	0.11	0.19	68.10
22.21	-861.26	20.52	0.10	0.20	67.28
29.29	-872.02	22.55	0.11	0.21	65.14
36.36	-881.57	24.77	0.11	0.22	63.29
40.00	-886.86	25.39	0.12	0.23	62.38
43.43	-889.93	26.41	0.12	0.23	61.76
50.50	-917.82	25.99	0.14	0.25	60.51
57.57	-927.50	28.69	0.15	0.27	59.35
60.00	-917.14	33.08	0.15	0.26	59.18
64.64	-920.62	38.60	0.15	0.27	58.73
71.71	-925.22	45.18	0.17	0.31	57.82
78.79	-928.03	51.83	0.18	0.31	57.35
85.86	-932.34	57.31	0.17	0.31	57.15
92.93	-932.98	60.65	0.18	0.38	56.93
100.00	-909.17	74.27	0.23	0.43	56.36

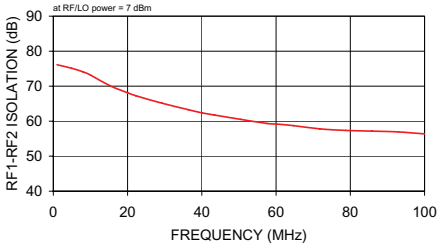
SYPD-1
DC OUTPUT



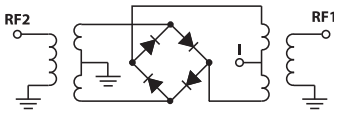
SYPD-1
DC OFFSET



SYPD-1
RF1-RF2 ISOLATION



electrical schematic



Notes

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp

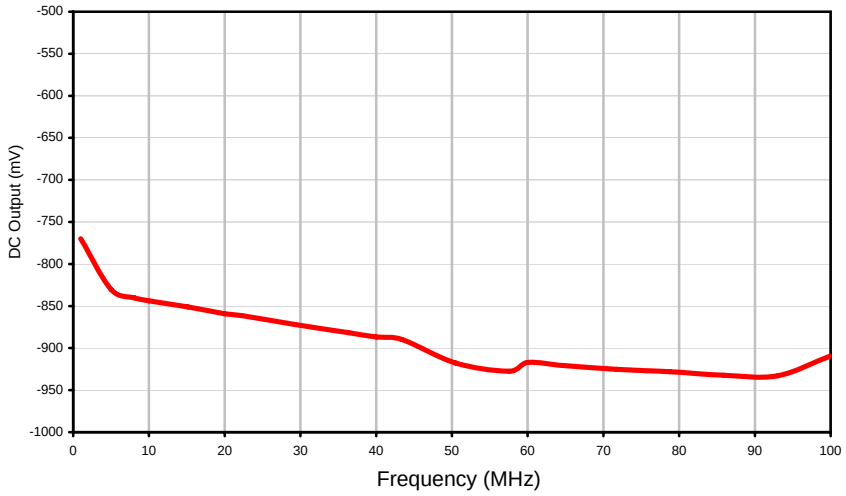
Phase Detector (High DC Output) SYPD-1+

Typical Performance Data

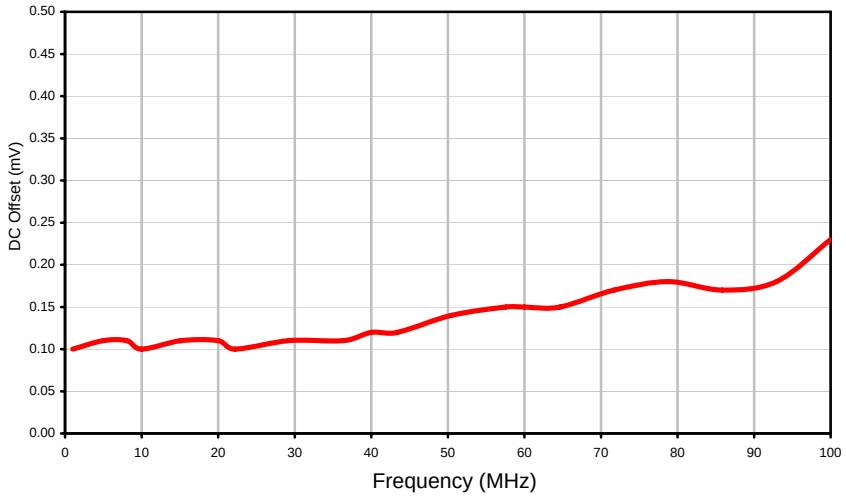
FREQUENCY (MHz)	DC OUTPUT (mV)	DC OFFSET (mV)	RF1-RF2 ISOLATION (dB)
1.00	-769.98	0.10	76.12
5.00	-830.34	0.11	75.09
8.07	-840.24	0.11	74.07
10.00	-843.71	0.10	73.19
15.14	-851.12	0.11	70.19
20.00	-859.20	0.11	68.10
22.21	-861.26	0.10	67.28
29.29	-872.02	0.11	65.14
36.36	-881.57	0.11	63.29
40.00	-886.86	0.12	62.38
43.43	-889.93	0.12	61.76
50.50	-917.82	0.14	60.51
57.57	-927.50	0.15	59.35
60.00	-917.14	0.15	59.18
64.64	-920.62	0.15	58.73
71.71	-925.22	0.17	57.82
78.79	-928.03	0.18	57.35
85.86	-932.34	0.17	57.15
92.93	-932.98	0.18	56.93
100.00	-909.17	0.23	56.36

Typical Performance Curves

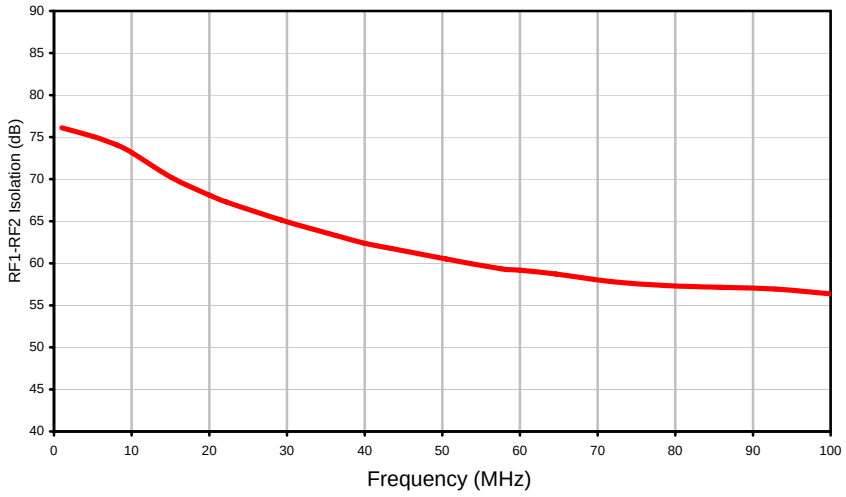
DC Output



DC Offset



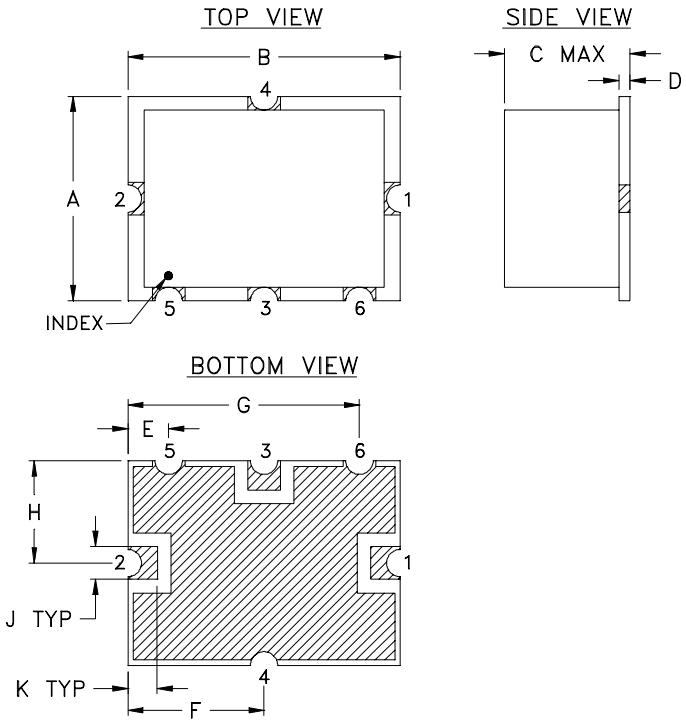
RF1-RF2 Isolation



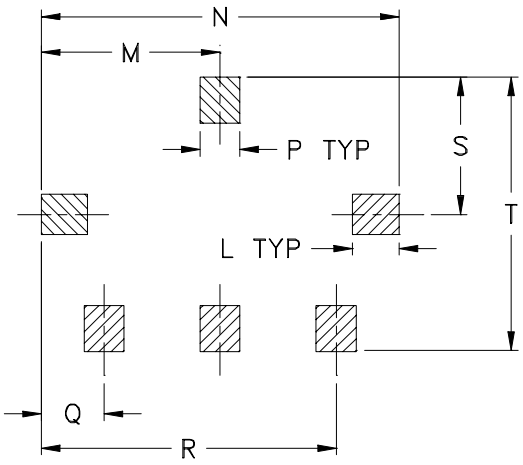
Case Style TTT

Outline Dimensions

TTT166
TTT167



PCB Land Pattern



Suggested Layout,
Tolerance to be within ±.002

CASE #	A	B	C	D	E	F	G	H	J	K	L	M	N
TTT166	.38 (9.65)	.50 (12.70)	.15 (3.81)	.020 (0.51)	.075 (1.91)	.250 (6.35)	.425 (10.80)	.187 (4.75)	.050 (1.27)	.050 (1.27)	.070 (1.78)	.270 (6.86)	.540 (13.72)
TTT167			.23 (5.84)										

CASE #	P	Q	R	S	T	WT. GRAM
TTT166	.060 (1.52)	.095 (2.41)	.445 (11.30)	.208 (5.28)	.415 (10.54)	.8
TTT167						.8

Dimensions are in inches (mm). Tolerances: 2 Pl. ± .01; 3 Pl. ± .005

Note:

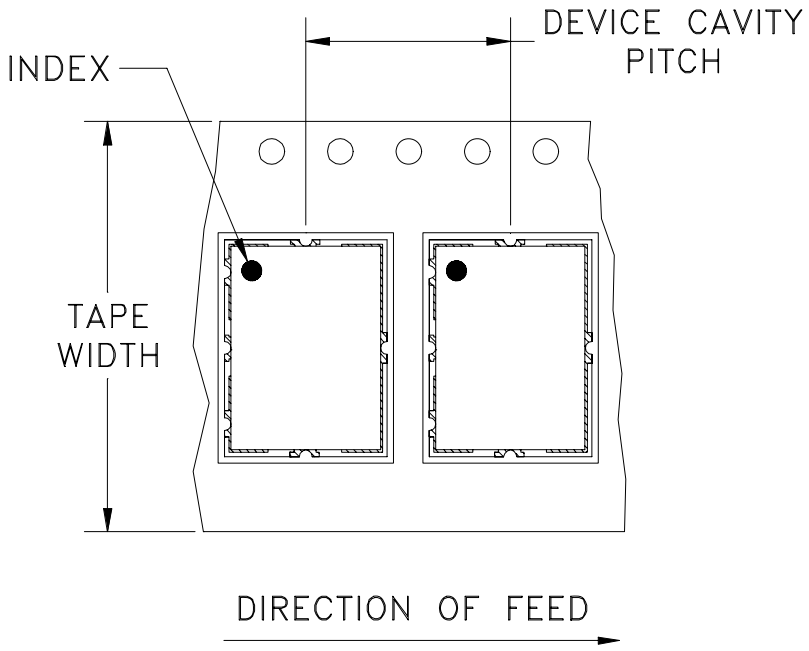
1. Case material: Plastic.
2. Base material: Printed wiring laminate.
3. Termination finish:
   For RoHS Case Styles: 3-5 µ inch (.08-.13 microns) Gold over 120-240 µ inch (3.05-6.10 microns) Nickel plate. All models, (+) suffix.
   For RoHS-5 Case Styles: Tin-Lead plate. All models, no (+) suffix.

Mini-Circuits®
INTERNET http://www.minicircuits.com
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661
Distribution Centers NORTH AMERICA 800-654-7949 • 417-335-5935 • Fax 417-335-5945 • EUROPE 44-1252-832600 • Fax 44-1252-837010
Mini-Circuits ISO 9001 & ISO 14001 Certified

This document and its contents are the property of Mini-Circuits.

Tape & Reel Packaging TR-F12

DEVICE ORIENTATION IN T&R



Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel	
24	12	7	Small quantity standards (see note)	10
				20
				50
				100
				200
		13	Standard	500

Note: Please Consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf

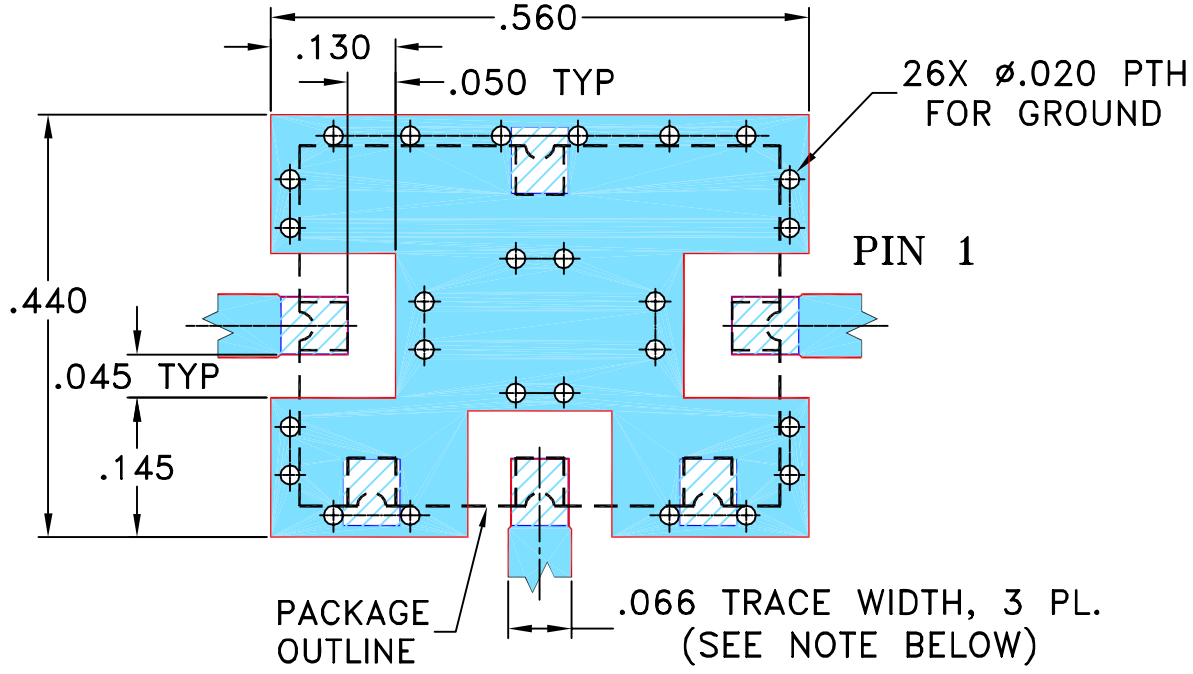
Mini-Circuits®
INTERNET http://www.minicircuits.com
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661
Distribution Centers NORTH AMERICA 800-654-7949 • 417-335-5935 • Fax 417-335-5945 • EUROPE 44-1252-832600 • Fax 44-1252-837010
Mini-Circuits ISO 9001 & ISO 14001 Certified

This document and its contents are the property of Mini-Circuits.1

THIRD ANGLE PROJECTION

REVISIONS					
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
A	M86762	ADDED CONNECTIONS "lp & lq"	05/23/03	MMG	WL
B	M94598	ADDED CONNECTION "hk"	10/08/04	MMG	HY
C	M102713	UPDATED NOTES & DESCRIPTION	01/14/06	GF	IL
D	M132989	UPDATED NOTE 2	08/24/11	GF	DJ

SUGGESTED MOUNTING CONFIGURATION FOR TTT166/167 CASE STYLE, "hk"/"lp"/"lq" "x"/"ck"/"ec" PIN CONNECTIONS



NOTE:

1. TRACE WIDTH IS SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .030" ± .002"; COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. THE USE OF SOLDER MASK OVER THE GROUND AREA UNDER THE UNIT AS SHOWN IS RECOMMENDED TO PREVENT POTENTIAL SHORTING. IF USER CHOOSES TO EXPOSE METAL UNDER THE ENTIRE UNIT GROUND PAD FOR IMPROVED GROUNDING, IT IS RECOMMENDED A SOLDER MASK DAM BE APPLIED AROUND EACH GROUND PAD TO ENSURE FILLET AND CONNECTION AT GROUND PADS.
3. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER), SEE NOTE 2.

DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

UNLESS OTHERWISE SPECIFIED		INITIALS	DATE
DIMENSIONS ARE IN INCHES	DRAWN	GF	03/18/03
TOLERANCES ON:	CHECKED	IL	04/15/03
2 PL DECIMALS ±	APPROVED	DJ	04/15/03
3 PL DECIMALS ± .005			
ANGLES ±			
FRACTIONS ±			

Mini-Circuits®
THIS DOCUMENT AND ITS CONTENTS ARE THE PROPERTY OF MINI-CIRCUITS. EXCEPT FOR USE EXPRESSLY GRANTED, IN WRITING, TO ITS VENDORS, VENDEE AND THE UNITED STATES GOVERNMENT, MINI-CIRCUITS RESERVES ALL PROPRIETARY DESIGN, USE , MANUFACTURING AND REPRODUCTION RIGHTS THERETO. THESE CONTENTS SHALL NOT BE USED, DUPLICATED OR DISCLOSED TO ANY OUTSIDE PARTY, IN WHOLE OR IN PART, WITHOUT WRITTEN PERMISSION OF MINI-CIRCUITS.

ASHEETA1.DWG REV:A DATE:01/12/95

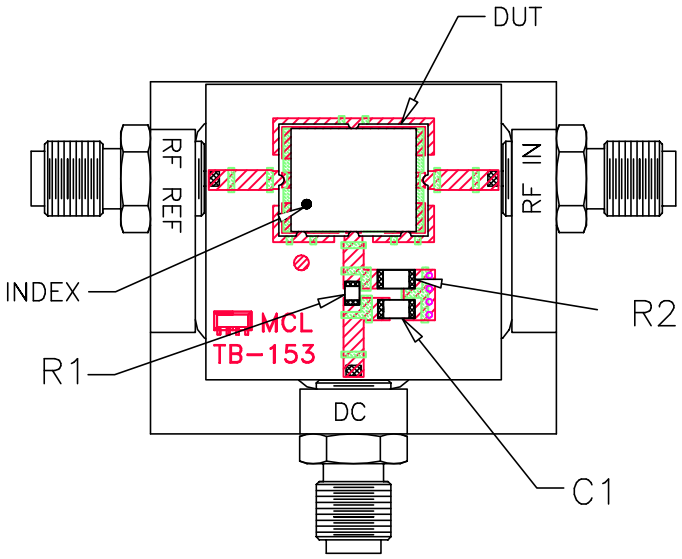
Mini-Circuits® 13 Neptune Avenue Brooklyn NY 11235

PL, hk/lp/lq/x/ck/ec, TTT166/167, SYM/HJK/SYAS/SYPD, TB-12

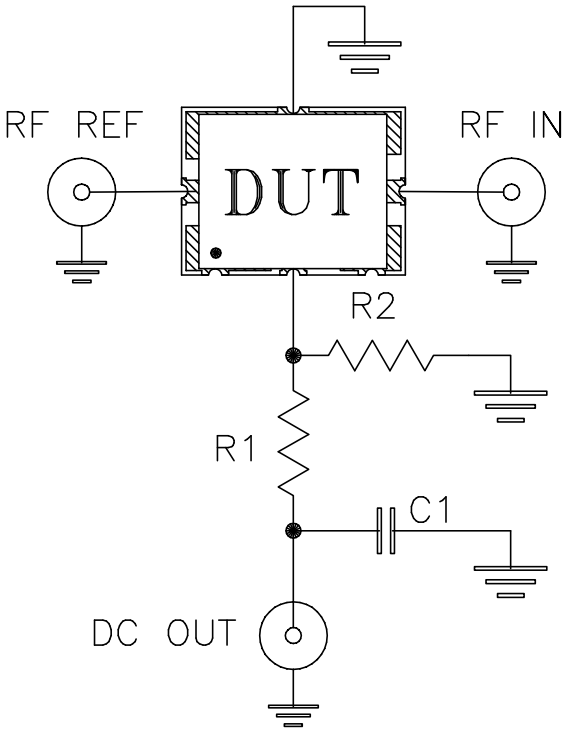
SIZE	CODE IDENT	DRAWING NO:	REV:
A	15542	98-PL-079	D

FILE:	SCALE:	SHEET:
98PL079	5:1	1 OF 1

Evaluation Board and Circuit



TB-153



COMPONENT	VALUE	SIZE
C1	Capacitor 0.10 uF	1206
R1	Resistor 5620 Ohm	0805
R2	Resistor 499 Ohm	1206

Schematic Diagram

Notes:

1. 50 Ohm SMA Female connectors.
2. PCB Material: RO4350 or equivalent, Dielectric Constant=3.5, Thickness=.020 inch.

Mini-Circuits®

THIS DOCUMENT AND ITS CONTENTS ARE THE PROPERTY OF MINI-CIRCUITS.

Mini-Circuits

Environmental Specifications ENV02T1

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215

This document and its contents are the property of Mini-Circuits.